



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE6711GL			<b>Issued</b>	2. August 2018			
<b>MA#</b>	MA000554012							
<b>Package</b>	PG-DSO-20-36			<b>Weight*</b>	487.09 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.583	1.15	1.15	11461	11461
leadframe	inorganic material	phosphorus	7723-14-0	0.039	0.01		80	
	non noble metal	zinc	7440-66-6	0.155	0.03		319	
	non noble metal	iron	7439-89-6	3.104	0.64		6373	
wire	non noble metal	copper	7440-50-8	126.041	25.88	26.56	258762	265534
	noble metal	gold	7440-57-5	0.544	0.11	0.11	1116	1116
	encapsulation	organic material	carbon black	1333-86-4	0.690	0.14		1416
encapsulation	plastics	epoxy resin	-	31.737	6.52		65157	
	inorganic material	silicondioxide	60676-86-0	312.545	64.16	70.82	641655	708228
leadfinish	non noble metal	tin	7440-31-5	2.746	0.56	0.56	5637	5637
plating	noble metal	silver	7440-22-4	1.621	0.33	0.33	3329	3329
glue	plastics	epoxy resin	-	0.572	0.12		1174	
	noble metal	silver	7440-22-4	1.715	0.35	0.47	3521	4695
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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